

ELECTRICAL CHARACTERISTICS AND RATINGS**Fast thyristors****Blocking - Off State**

V_{RRM} (1)	V_{DRM} (1)	V_{RSM} (1)
3000	3000	3100

 V_{RRM} = Repetitive peak reverse voltage V_{DRM} = Repetitive peak off state voltage V_{RSM} = Non repetitive peak reverse voltage (2)

Repetitive peak reverse leakage and off state	I_{RRM} / I_{DRM}	100 mA
Critical rate of voltage rise	dV/dt (4)	1000 V/ μ sec

Type: YZPST 63H200**Notes:**All ratings are specified for $T_j=25^\circ\text{C}$ unless otherwise stated.

(1) All voltage ratings are specified for an applied

50Hz/60Hz sinusoidal waveform over the temperature range -40 to +125 °C.

(2) 10 msec. max. pulse width

(3) Maximum value for $T_j = 125^\circ\text{C}$.(4) Minimum value for linear and exponential waveshape to 80% rated V_{DRM} . Gate open. $T_j = 125^\circ\text{C}$.

(5) Non-repetitive value.

(6) The value of di/dt is established in accordancewith EIA/NIMA Standard RS-397, Section 5-2-2-6. The value defined would be in addition to that obtained from a snubber circuit, comprising a 0.2 μ F capacitor and 20 ohms resistance in parallel with the thristor under test.**Conducting - on state**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Average value of on-state current	$I_{T(AV)M}$		1000		A	Sinewave, 180° conduction, $T_{sink}=55^\circ\text{C}$
RMS value of on-state current	I_{TRMS}		1700		A	Nominal value
Peak one cPSTCle surge (non repetitive) current	I_{TSM}		15.9		KA	10.0 msec (50Hz), sinusoidal wave-shape, 180° conduction, $T_j = 125^\circ\text{C}$
I^2t	I^2t		1.26×10^6		A^2s	10.0 msec
Latching current	I_L		-		mA	$V_D = 24\text{ V}$; $R_L = 12\text{ ohms}$
Holding current	I_H		1000		mA	$V_D = 24\text{ V}$; $I = 2.5\text{ A}$
Peak on-state voltage	V_{TM}		2.42		V	$I_{TM} = 2000\text{ A}$; $T_j = 125^\circ\text{C}$
Critical rate of rise of on-state current (5, 6)	di/dt		-		$\text{A}/\mu\text{s}$	Switching from $V_{DRM} \leq 1000\text{ V}$, non-repetitive
Critical rate of rise of on-state current (6)	di/dt		150		$\text{A}/\mu\text{s}$	Switching from $V_{DRM} \leq 1000\text{ V}$



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Gating

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Peak gate power dissipation	P _{GM}		30		W	t _p = 40 us
Average gate power dissipation	P _{G(AV)}		5		W	
Peak gate current	I _{GM}		-		A	
Gate current required to trigger all units	I _{GT}		-	300	mA	V _D = 6 V; R _L = 3 ohms; T _j = -40 °C
			-		mA	V _D = 6 V; R _L = 3 ohms; T _j = +25 °C
			-		mA	V _D = 6 V; R _L = 3 ohms; T _j = +125 °C
Gate voltage required to trigger all units	V _{GT}		-	3.0	V	V _D = 6 V; R _L = 3 ohms; T _j = -40 °C
			-		V	V _D = 6 V; R _L = 3 ohms; T _j = 0-125°C
			-		V	V _D = Rated V _{DRM} ; R _L = 1000 ohms; T _j = + 125 °C
Peak negative voltage	V _{GRM}		5		V	

Dynamic

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Delay time	t _d		1.6	0.8	μs	I _{TM} = 500 A; V _D = Rated V _{DRM} Gate pulse: V _G = 20 V; R _G = 20 ohms; t _r = 0.1 μs; t _p = 20 μs
Turn-off time (with V _R = -50 V)	t _q		-	120	μs	I _{TM} = 1000 A; di/dt = 25 A/μs; V _R ≥ -50 V; Re-applied dV/dt = 20 V/μs linear to 80% V _{DRM} ; V _G = 0; T _j = 125 °C; Duty cPSTCle ≥ 0.01%
Reverse recovery charge	Q _{rr}		-	-	μC	I _{TM} = 1000 A; di/dt = 25 A/μs; V _R ≥ -50 V

* For guaranteed max. value, contact factory.

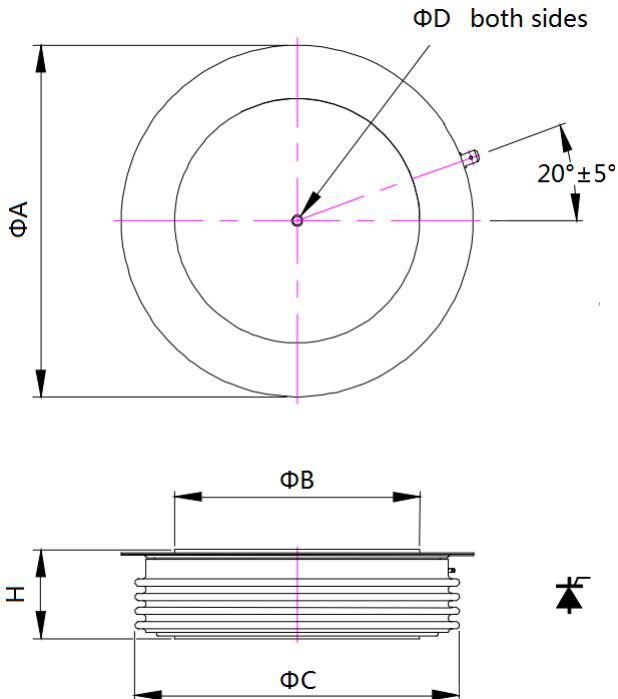
THERMAL AND MECHANICAL CHARACTERISTICS AND RATINGS

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Operating temperature	T _j	-40	+125		°C	
Storage temperature	T _{stg}	-40	+150		°C	
Thermal resistance - junction to case	R _{θ (j-c)}		-		K/W	Double sided cooled Single sided cooled
Thermal resistance - case to heatsink	R _{θ (c-s)}		-		K/W	Double sided cooled Single sided cooled
Thermal resistance - junction to heatsink	R _{θ (j-s)}		0.022 0.044		K/W	Double sided cooled Single sided cooled
Mounting force	P	19	26		kN	
Weight	W			510	g	about

* Mounting surfaces smooth, flat and greased

Note : for case outline and dimensions, see case outline drawing in last page of this Technical Data



CASE OUTLINE AND DIMENSIONS.

Sym	A	B	C	D	H
mm	75	47	66	3.5×3	26±1